Features:

1. Chip material: GaAsP/GaP (Yellow)

2. Emitted color: Yellow

3. Lens Appearance: Yellow Diffused

4. Designed for ease in circuit board assembly.

5. Black case enhance contrast ratio.

6. Solid state light source.

7. Reliable and rugged.

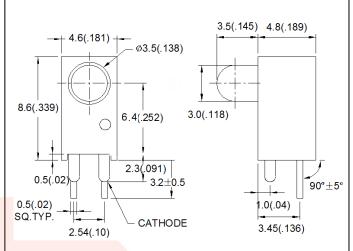
8. 3mm diameter package

9. This product don't contained restriction substance, compliance ROHS standard.

Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Package dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Yellow	Unit
Power Dissipation	Pd	80	mW
Forward Current	I _F	30	mA
Peak Forward Current*1	I _{FP}	150	mA
Reverse Voltage	V _R	5	V
Operating Temperature	Topr	-40℃~+85℃	
Storage Temperature	Tstg	-40℃~+100℃	
Soldering Temperature	Tsol	260°C (for 5 seconds)	

^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.



■ Electrical and optical characteristics(Ta=25°C)

Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	I _F =20mA	Yellow	1.8	-	2.4	V
Luminous Intensity	lv	I _F =20mA	Yellow	20	-	80	mcd
Reverse Current	I _R	V _R =5V	Yellow	-	-	100	μΑ
Peak Wave Length	λр	I _F =20mA	Yellow	-	590	-	nm
Dominant Wave Length	λd	I _F =20mA	Yellow	585	•	595	nm
Spectral Line Half-width	Δλ	I _F =20mA	Yellow	-	35	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	Yellow	-	40	-	deg

Typical Electro-Optical Characteristics Curves

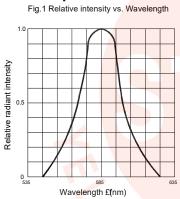
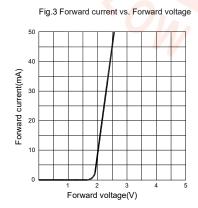


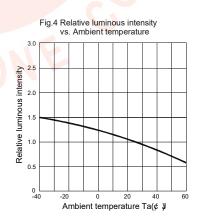
Fig. 2 Forward current derating curve vs. Ambient temperature

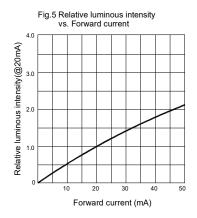
Fig. 2 Forward current derating curve vs. Ambient temperature

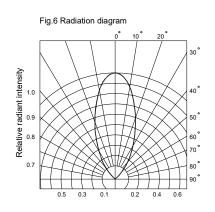
Fig. 2 Forward current derating curve vs. Ambient temperature

Ambient temperature Ta(¢)



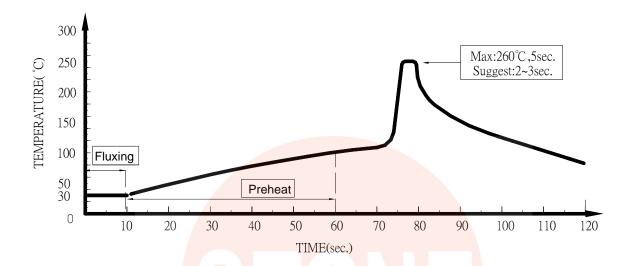








Dip Soldering



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A: Max: 350°C Within 3 sec. One time only.

B: For 3mm LED without flange, if the LED epoxy lays flat on the PCB, the welding condition is 350°C within 2 seconds, one time only.

